

PATENT ASSIGNMENT COVER SHEET

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SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT
CONVEYING PARTY DATA	
Name	Execution Date
YAN-HAN CHEN	10/15/2019
CHENG-KANG HU	10/15/2019
REN-HAU WU	10/15/2019
CHENG-HUNG CHEN	10/15/2019
FENG-KUANG WU	10/16/2019
HSU-SHUI LIU	10/15/2019
JIUN-RONG PAI	10/16/2019
SHOU-WEN KUO	10/16/2019
RECEIVING PARTY DATA	
Name:	TAIWAN SEMICONDUCTOR MANUFACTURING COMPANY LIMITED
Street Address:	NO. 8, LI-HSIN ROAD 6, HSIN-CHU SCIENCE PARK
City:	HSIN-CHU
State/Country:	TAIWAN
Postal Code:	300-77
PROPERTY NUMBERS Total: 1	
Property Type	Number
Application Number:	16572960
CORRESPONDENCE DATA	
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ATTORNEY DOCKET NUMBER:	P20183298US00
NAME OF SUBMITTER:	WILLIAM JOSEPH COOPER
SIGNATURE:	/William Joseph Cooper/

DATE SIGNED:	10/21/2019
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Total Attachments: 3

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ASSIGNMENT

For good and valuable consideration received of the hereinafter named assignee, receipt of which is hereby acknowledged, the undersigned

Yan-Han CHEN
Miaoli County, TW

Cheng-Kang HU
Kaohsiung City, TW

Ren-Hau WU
New Taipei City, TW

Cheng-Hung CHEN
Zhubei City, TW

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Hsu-Shui LIU
Pingjhen City, TW

Jiun-Rong PAI
Zhubei City, TW

Shou-Wen KUO
Hsinchu City, TW

NOW, THEREFORE, for and in consideration of our employment and the salary or wages paid to us by Taiwan Semiconductor Manufacturing Company Limited, I/we, Yan-Han CHEN, Cheng-Kang HU, Ren-Hau WU, Cheng-Hung CHEN, Feng-Kuang WU, Hsu-Shui LIU, Jiun-Rong PAI, and Shou-Wen KUO by these presents do sell, assign, and transfer unto said Taiwan Semiconductor Manufacturing Company Limited, a corporation organized and existing under the laws of the Republic of China, having its principal place of business at No. 8, Li-Hsin Road 6, Hsin-Chu Science Park, Hsin-Chu, Taiwan 300-77, R.O.C., is desirous of acquiring an interest therein, its successors and assigns, the entire right, title and interest, so far as concerns the United States and the Territories and Possessions thereof and all foreign countries, in and to the inventions entitled

DEVICE POSITIONING USING SENSORS

for which application for United States Letters Patent has been filed on September 17, 2019 under Serial No. 16/572,960, or was executed by the undersigned on the date below and is being filed concurrently herewith, said application for United States Letters Patent, any and all other applications for Letters Patent on said inventions in countries foreign to the United States, including all divisional, renewal, substitute, continuation and Convention applications based in whole or in part upon said inventions or upon said applications, and any and all Letters Patent and reissues and extensions of Letters Patent granted for said inventions or upon said applications, and every priority right that is or may be predicated upon or arise from said inventions, said applications and said Letters Patent; said assignee being hereby authorized to file patent applications in any or all countries on any or all said inventions in the name of the undersigned or in the name of said assignee or otherwise as said assignee may deem advisable, under the International Convention or otherwise; the Commissioner of Patents and Trademarks of the United States of America and the empowered officials of all other governments being hereby authorized to issue or transfer all said Letters Patent to said assignee in accordance herewith; this assignment being under covenant, not only that full power to make the same is had

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by the undersigned, but also that such assigned right is not encumbered by any grant, license, or other right heretofore given, and that the undersigned will do all acts reasonably serving to assure that said inventions, patent applications and Letters Patent shall be held and enjoyed by said assignee as fully and entirely as the same could have been held and enjoyed by the undersigned if this assignment had not been made, and particularly to execute and deliver to said assignee all lawful documents including petitions, specifications, oaths, assignments, invention disclaimers, and lawful affidavits in form and substance which may be requested by said assignee, to furnish said assignee with all facts relating to said inventions or the history thereof and any and all documents, photographs, models, samples or other physical exhibits which may be useful for establishing the facts of conception, disclosure and reduction to practice of said inventions, and to testify in any proceedings relating to said inventions, patent applications and Letters Patent.

<u>Yan-Han CHEN</u>	<u>2019/10/15</u>
Inventor's Signature	Date
<u>Yan-Han CHEN</u>	
Printed Name in English	

<u>Cheng-Kang Hu</u>	<u>2019/10/15</u>
Inventor's Signature	Date
<u>Cheng-Kang HU</u>	
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<u>Ren-Hau Wu</u>	<u>2019/10/15</u>
Inventor's Signature	Date
<u>Ren-Hau WU</u>	
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<u>Cheng-Hung Chen</u>	<u>15th Dec, 2019</u>
Inventor's Signature	Date
<u>Cheng-Hung CHEN</u>	
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<u>Feng Kuang Wu</u> Inventor's Signature	<u>2019.10.16</u> Date
<u>Feng-Kuang WU</u> Printed Name in English	

<u>Hsu Shui Liu</u> Inventor's Signature	<u>2019.10.15</u> Date
<u>Hsu-Shui LIU</u> Printed Name in English	

<u>Jiun-Rong Pai</u> Inventor's Signature	<u>2019.10.16</u> Date
<u>Jiun-Rong PAI</u> Printed Name in English	

<u>Shou-Wen Kuo</u> Inventor's Signature	<u>2019.10.16</u> Date
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10/15/2019